Intel - EP1S60F1020C5 Datasheet





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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	5712
Number of Logic Elements/Cells	57120
Total RAM Bits	5215104
Number of I/O	773
Number of Gates	
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1020-BBGA
Supplier Device Package	1020-FBGA (33x33)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1s60f1020c5

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Typographic Conventions

This document uses the typographic conventions shown below.

Visual Cue	Meaning			
Bold Type with Initial Capital Letters	Command names, dialog box titles, checkbox options, and dialog box options are shown in bold, initial capital letters. Example: Save As dialog box.			
bold type	External timing parameters, directory names, project names, disk drive names, filenames, filename extensions, and software utility names are shown in bold type. Examples: f _{MAX} , \qdesigns directory, d: drive, chiptrip.gdf file.			
Italic Type with Initial Capital Letters	Document titles are shown in italic type with initial capital letters. Example: AN 75: High-Speed Board Designs.			
Italic type	Internal timing parameters and variables are shown in italic type. Examples: $t_{P A}$, $n + 1$.			
	Example: <i>stile names, sproject names.</i>			
Initial Capital Letters	Keyboard keys and menu names are shown with initial capital letters. Examples: Delete key, the Options menu.			
"Subheading Title"	References to sections within a document and titles of on-line help topics are shown in quotation marks. Example: "Typographic Conventions."			
Courier type	Signal and port names are shown in lowercase Courier type. Examples: data1, tdi, input. Active-low signals are denoted by suffix n, e.g., resetn.			
	Anything that must be typed exactly as it appears is shown in Courier type. For example: c:\qdesigns\tutorial\chiptrip.gdf. Also, sections of an actual file, such as a Report File, references to parts of files (e.g., the AHDL keyword SUBDESIGN), as well as logic function names (e.g., TRI) are shown in Courier.			
1., 2., 3., and a., b., c., etc.	Numbered steps are used in a list of items when the sequence of the items is important, such as the steps listed in a procedure.			
••	Bullets are used in a list of items when the sequence of the items is not important.			
\checkmark	The checkmark indicates a procedure that consists of one step only.			
	The hand points to information that requires special attention.			
4	The angled arrow indicates you should press the Enter key.			
••••	The feet direct you to more information on a particular topic.			



Figure 2–3. Direct Link Connection

LAB Control Signals

Each LAB contains dedicated logic for driving control signals to its LEs. The control signals include two clocks, two clock enables, two asynchronous clears, synchronous clear, asynchronous preset/load, synchronous load, and add/subtract control signals. This gives a maximum of 10 control signals at a time. Although synchronous load and clear signals are generally used when implementing counters, they can also be used with other functions.

Each LAB can use two clocks and two clock enable signals. Each LAB's clock and clock enable signals are linked. For example, any LE in a particular LAB using the labclk1 signal will also use labclkena1. If the LAB uses both the rising and falling edges of a clock, it also uses both LAB-wide clock signals. De-asserting the clock enable signal will turn off the LAB-wide clock.

Each LAB can use two asynchronous clear signals and an asynchronous load/preset signal. The asynchronous load acts as a preset when the asynchronous load data input is tied high.

row connections in a four-LAB region. Every LAB has its own set of R4 interconnects to drive either left or right. Figure 2–9 shows R4 interconnect connections from an LAB. R4 interconnects can drive and be driven by DSP blocks and RAM blocks and horizontal IOEs. For LAB interfacing, a primary LAB or LAB neighbor can drive a given R4 interconnect. For R4 interconnects that drive to the right, the primary LAB and right neighbor can drive on to the interconnect. For R4 interconnects can drive other R4 interconnects that drive to the left, the primary LAB and its left neighbor can drive on to the interconnects can drive other R4 interconnects to extend the range of LABs they can drive. R4 interconnects can also drive C4 and C16 interconnects for connections from one row to another. Additionally, R4 interconnects can drive R24 interconnects.





Notes to Figure 2–9:

(1) C4 interconnects can drive R4 interconnects.

(2) This pattern is repeated for every LAB in the LAB row.

The R8 interconnects span eight LABs, M512 or M4K RAM blocks, or DSP blocks to the right or left from a source LAB. These resources are used for fast row connections in an eight-LAB region. Every LAB has its own set of R8 interconnects to drive either left or right. R8 interconnect connections between LABs in a row are similar to the R4 connections shown in Figure 2–9, with the exception that they connect to eight LABs to the right or left, not four. Like R4 interconnects, R8 interconnects can drive and be driven by all types of architecture blocks. R8 interconnects



Figure 2–26. Input/Output Clock Mode in Simple Dual-Port Mode Notes (1), (2)

Notes to Figure 2–26:

- (1) All registers shown except the rden register have asynchronous clear ports.
- (2) Violating the setup or hold time on the address registers could corrupt the memory contents. This applies to both read and write operations.



Figure 2–29. DSP Blocks Arranged in Columns



Figure 2–30. DSP Block Diagram for 18 × 18-Bit Configuration

Enhanced PLLs

Stratix devices contain up to four enhanced PLLs with advanced clock management features. Figure 2–52 shows a diagram of the enhanced PLL.



Notes to Figure 2–52:

- (1) External feedback is available in PLLs 5 and 6.
- (2) This single-ended external output is available from the *g*0 counter for PLLs 11 and 12.
- (3) These four counters and external outputs are available in PLLs 5 and 6.
- (4) This connection is only available on EP1S40 and larger Stratix devices. For example, PLLs 5 and 11 are adjacent and PLLs 6 and 12 are adjacent. The EP1S40 device in the 780-pin FineLine BGA package does not support PLLs 11 and 12.



Figure 2–55. External Clock Outputs for PLLs 5 & 6

Notes to Figure 2-55:

- (1) The design can use each external clock output pin as a general-purpose output pin from the logic array. These pins are multiplexed with IOE outputs.
- (2) Two single-ended outputs are possible per output counter—either two outputs of the same frequency and phase or one shifted 180°.
- (3) EP1S10, EP1S20, and EP1S25 devices in 672-pin BGA and 484- and 672-pin FineLine BGA packages only have two pairs of external clocks (i.e., pll_out0p, pll_out0n, pll_out1p, and pll_out1n).
- (4) Differential SSTL and HSTL outputs are implemented using two single-ended output buffers, which are programmed to have opposite polarity.

Figure 2–59. Stratix IOE Structure



The IOEs are located in I/O blocks around the periphery of the Stratix device. There are up to four IOEs per row I/O block and six IOEs per column I/O block. The row I/O blocks drive row, column, or direct link interconnects. The column I/O blocks drive column interconnects. Figure 2–60 shows how a row I/O block connects to the logic array. Figure 2–61 shows how a column I/O block connects to the logic array.

Stratix devices have an I/O interconnect similar to the R4 and C4 interconnect to drive high-fanout signals to and from the I/O blocks. There are 16 signals that drive into the I/O blocks composed of four output enables io_boe [3..0], four clock enables io_bce [3..0], four clocks io_bclk [3..0], and four clear signals io_bclr [3..0]. The pin's datain signals can drive the IO interconnect, which in turn drives the logic array or other I/O blocks. In addition, the control and data signals can be driven from the logic array, providing a slower but more flexible routing resource. The row or column IOE clocks, io_clk [7..0], provide a dedicated routing resource for low-skew, high-speed clocks. I/O clocks are generated from regional, global, or fast regional clocks (see "PLLs & Clock Networks" on page 2–73). Figure 2–62 illustrates the signal paths through the I/O block.







Figure 2–65. Stratix IOE in DDR Input I/O Configuration Note (1)

Notes to Figure 2–65:

- (1) All input signals to the IOE can be inverted at the IOE.
- (2) This signal connection is only allowed on dedicated DQ function pins.
- (3) This signal is for dedicated DQS function pins only.

Table 2–27. DQS & DQ Bus Mode Support (Part 2 of 2			?) Note (1)			
Device	Package	Number of ×8 Groups	Number of ×16 Groups	Number of ×32 Groups		
EP1S25	672-pin BGA 672-pin FineLine BGA	16 (3)	8	4		
	780-pin FineLine BGA 1,020-pin FineLine BGA	20	8	4		
EP1S30	956-pin BGA 780-pin FineLine BGA 1,020-pin FineLine BGA	20	8	4		
EP1S40	956-pin BGA 1,020-pin FineLine BGA 1,508-pin FineLine BGA	20	8	4		
EP1S60	956-pin BGA 1,020-pin FineLine BGA 1,508-pin FineLine BGA	20	8	4		
EP1S80	956-pin BGA 1,508-pin FineLine BGA 1,923-pin FineLine BGA	20	8	4		

Notes to Table 2–27:

 See the Selectable I/O Standards in Stratix & Stratix GX Devices chapter in the Stratix Device Handbook, Volume 2 for V_{REF} guidelines.

(2) These packages have six groups in I/O banks 3 and 4 and six groups in I/O banks 7 and 8.

(3) These packages have eight groups in I/O banks 3 and 4 and eight groups in I/O banks 7 and 8.

(4) This package has nine groups in I/O banks 3 and 4 and nine groups in I/O banks 7 and 8.

(5) These packages have three groups in I/O banks 3 and 4 and four groups in I/O banks 7 and 8.

A compensated delay element on each DQS pin automatically aligns input DQS synchronization signals with the data window of their corresponding DQ data signals. The DQS signals drive a local DQS bus in the top and bottom I/O banks. This DQS bus is an additional resource to the I/O clocks and is used to clock DQ input registers with the DQS signal.

Two separate single phase-shifting reference circuits are located on the top and bottom of the Stratix device. Each circuit is driven by a system reference clock through the CLK pins that is the same frequency as the DQS signal. Clock pins CLK [15..12] p feed the phase-shift circuitry on the top of the device and clock pins CLK [7..4] p feed the phase-shift circuitry on the bottom of the device. The phase-shifting reference circuit on the top of the device controls the compensated delay elements for all 10 DQS pins located at the top of the device. The phase-shifting reference circuit on the bottom of the device controls the compensated delay elements for all 10 DQS pins located on the bottom of the device. All 10 delay elements (DQS signals) on either the top or bottom of the device.

The Quartus II MegaWizard[®] Plug-In Manager only allows the implementation of up to 20 receiver or 20 transmitter channels for each fast PLL. These channels operate at up to 840 Mbps. The receiver and transmitter channels are interleaved such that each I/O bank on the left and right side of the device has one receiver channel and one transmitter channel per LAB row. Figure 2–74 shows the fast PLL and channel layout in EP1S10, EP1S20, and EP1S25 devices. Figure 2–75 shows the fast PLL and channel layout in the EP1S30 to EP1S80 devices.



Figure 2–74. Fast PLL & Channel Layout in the EP1S10, EP1S20 or EP1S25 Devices Note (1)

Notes to Figure 2–74:

- (1) Wire-bond packages support up to 624 Mbps.
- (2) See Table 2–41 for the number of channels each device supports.
- (3) There is a multiplexer here to select the PLL clock source. If a PLL uses this multiplexer to clock channels outside of its bank quadrant, those clocked channels support up to 840 Mbps for "high" speed channels and 462 Mbps for "low" speed channels, as labeled in the device pin-outs at www.altera.com.

- Stratix, Stratix II, Cyclone[®], and Cyclone II devices must be within the first 17 devices in a JTAG chain. All of these devices have the same JTAG controller. If any of the Stratix, Stratix II, Cyclone, and Cyclone II devices are in the 18th or after they will fail configuration. This does not affect SignalTap II.
- For more information on JTAG, see the following documents:
 - AN 39: IEEE Std. 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices
 - Jam Programming & Test Language Specification

SignalTap II Embedded Logic Analyzer

Stratix devices feature the SignalTap II embedded logic analyzer, which monitors design operation over a period of time through the IEEE Std. 1149.1 (JTAG) circuitry. You can analyze internal logic at speed without bringing internal signals to the I/O pins. This feature is particularly important for advanced packages, such as FineLine BGA[®] packages, because it can be difficult to add a connection to a pin during the debugging process after a board is designed and manufactured.

Configuration

The logic, circuitry, and interconnects in the Stratix architecture are configured with CMOS SRAM elements. Altera® devices are reconfigurable. Because every device is tested with a high-coverage production test program, you do not have to perform fault testing and can focus on simulation and design verification.

Stratix devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable configuration devices that configure Stratix devices via a serial data stream. Stratix devices can be configured in under 100 ms using 8-bit parallel data at 100 MHz. The Stratix device's optimized interface allows microprocessors to configure it serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat Stratix devices as memory and configure them by writing to a virtual memory location, making reconfigured in-circuit by resetting the device and loading new data. Real-time changes can be made during system operation, enabling innovative reconfigurable computing applications.

Operating Modes

The Stratix architecture uses SRAM configuration elements that require configuration data to be loaded each time the circuit powers up. The process of physically loading the SRAM data into the device is called configuration. During initialization, which occurs immediately after

Table 4–123. Stratix Maximum Output Clock Rate (Using I/O Pins) for PLL[1, 2, 3, 4] Pins in Wire-Bond Packages (Part 2 of 2)						
1/0 Standard -6 Speed -7 Speed -8 Speed						

I/O Standard	Grade	Grade	Grade	Unit
LVDS (2)	400	311	311	MHz
HyperTransport technology (2)	420	400	400	MHz

Notes to Tables 4–120 through 4–123:

- (1) Differential SSTL-2 outputs are only available on column clock pins.
- (2) These parameters are only available on row I/O pins.
- (3) SSTL-2 in maximum drive strength condition. See Table 4–101 on page 4–62 for more information on exact loading conditions for each I/O standard.
- (4) SSTL-2 in minimum drive strength with ≤ 10 pF output load condition.
- (5) SSTL-2 in minimum drive strength with > 10pF output load condition.
- (6) Differential SSTL-2 outputs are only supported on column clock pins.

PLL Specifications

Tables 4–127 through 4–129 describe the Stratix device enhanced PLL specifications.

Symbol	Parameter	Min	Тур	Max	Unit
f _{IN}	Input clock frequency	3 (1), (2)		684	MHz
f _{INPFD}	Input frequency to PFD	3		420	MHz
f _{INDUTY}	Input clock duty cycle	40		60	%
feinduty	External feedback clock input duty cycle	40		60	%
t _{INJITTER}	Input clock period jitter			±200 (3)	ps
t _{EINJITTER}	External feedback clock period jitter			±200 <i>(3)</i>	ps
t _{FCOMP}	External feedback clock compensation time (4)			6	ns
f _{out}	Output frequency for internal global or regional clock	0.3		500	MHz
f _{OUT_EXT}	Output frequency for external clock (3)	0.3		526	MHz
t _{outduty}	Duty cycle for external clock output (when set to 50%)	45		55	%
t _{JITTER}	Period jitter for external clock output (6)			±100 ps for >200-MHz outclk ±20 mUI for <200-MHz outclk	ps or mUI
t _{CONFIG5,6}	Time required to reconfigure the scan chains for PLLs 5 and 6			289/f _{SCANCLK}	
t _{CONFIG11,12}	Time required to reconfigure the scan chains for PLLs 11 and 12			193/f _{SCANCLK}	
t _{SCANCLK}	scanclk frequency (5)			22	MHz
t _{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays) (7)			100	μs
t _{LOCK}	Time required to lock from end of device configuration	10		400	μs
f _{VCO}	PLL internal VCO operating range	300		800 (8)	MHz
t _{LSKEW}	Clock skew between two external clock outputs driven by the same counter		±50		ps

Table 4–127. Enhanced PLL Specifications for -5 Speed Grades (Part 2 of 2)					
Symbol	Parameter	Min	Тур	Мах	Unit
t _{skew}	Clock skew between two external clock outputs driven by the different counters with the same settings		±75		ps
f _{SS}	Spread spectrum modulation frequency	30		150	kHz
% spread	Percentage spread for spread spectrum frequency (10)	0.4	0.5	0.6	%
t _{ARESET}	Minimum pulse width on areset signal	10			ns
t _{areset_recon} fig	Minimum pulse width on the areset signal when using PLL reconfiguration. Reset the PLL after scandataout goes high.	500			ns

Table 4–128. Enhanced PLL Specifications for -6 Speed Grades (Part 1 of 2)					
Symbol	Parameter	Min	Тур	Мах	Unit
f _{IN}	Input clock frequency	3 (1), (2)		650	MHz
f _{INPFD}	Input frequency to PFD	3		420	MHz
f _{INDUTY}	Input clock duty cycle	40		60	%
f _{EINDUTY}	External feedback clock input duty cycle	40		60	%
t _{INJITTER}	Input clock period jitter			±200 (3)	ps
t _{EINJITTER}	External feedback clock period jitter			±200 <i>(3)</i>	ps
t _{FCOMP}	External feedback clock compensation time (4)			6	ns
f _{OUT}	Output frequency for internal global or regional clock	0.3		450	MHz
f _{OUT_EXT}	Output frequency for external clock (3)	0.3		500	MHz
t _{outduty}	Duty cycle for external clock output (when set to 50%)	45		55	%
t _{JITTER}	Period jitter for external clock output (6)			±100 ps for >200-MHz outclk ±20 mUI for <200-MHz outclk	ps or mUI
t _{CONFIG5,6}	Time required to reconfigure the scan chains for PLLs 5 and 6			289/f _{SCANCLK}	
t _{CONFIG11,12}	Time required to reconfigure the scan chains for PLLs 11 and 12			193/f _{SCANCLK}	

Table 4–133. Fast PLL Specifications for -8 Speed Grades (Part 2 of 2)				
Symbol	Parameter	Min	Max	Unit
t _{ARESET}	Minimum pulse width on areset signal	10		ns

Notes to Tables 4–131 through 4–133:

(1) See "Maximum Input & Output Clock Rates" on page 4–76.

- (2) PLLs 7, 8, 9, and 10 in the EP1S80 device support up to 717-MHz input and output.
- (3) Use this equation ($f_{OUT} = f_{IN} * ml(n \times \text{post-scale counter})$) in conjunction with the specified f_{INPFD} and f_{VCO} ranges to determine the allowed PLL settings.
- (4) When using the SERDES, high-speed differential I/O mode supports a maximum output frequency of 210 MHz to the global or regional clocks (that is, the maximum data rate 840 Mbps divided by the smallest SERDES J factor of 4).
- (5) Refer to the section "High-Speed I/O Specification" on page 4-87 for more information.
- (6) This parameter is for high-speed differential I/O mode only.
- (7) These counters have a maximum of 32 if programmed for 50/50 duty cycle. Otherwise, they have a maximum of 16.
- (8) High-speed differential I/O mode supports W = 1 to 16 and J = 4, 7, 8, or 10.

DLL Specifications

Table 4–134 reports the jitter for the DLL in the DQS phase shift reference circuit.

Table 4–134. DLL Jitter for DQS Phase Shift Reference Circuit				
Frequency (MHz)	DLL Jitter (ps)			
197 to 200	± 100			
160 to 196	± 300			
100 to 159	± 500			

•••

For more information on DLL jitter, see the *DDR SRAM* section in the *Stratix Architecture* chapter of the *Stratix Device Handbook, Volume* 1.

Table 4–135 lists the Stratix DLL low frequency limit for full phase shift across all PVT conditions. The Stratix DLL can be used below these frequencies, but it will not achieve the full phase shift requested across all